

Appl. No. 09/730,932
Amdt. dated August 6, 2003

PATENT

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

- B'
-
- 1 1. (Currently Amended) A chip device comprising:
 - 2 a. a single, common leadframe comprising a base and a plurality of leads extending
 - 3 therefrom;
 - 4 b. a first die coupled to a first side of the base with solder;
 - 5 c. a second die coupled to a second side of the base opposite the first side with solder;
 - 6 and
 - 7 d. a molded body surrounding at least a portion of the leadframe and the dies.
 - 1 2. (Original) The chip device of claim 1 wherein at least one of the dies is a bumped die.
 - 1 3. (Original) The chip device of claim 2 wherein both dies are bumped dies.
 - 1 4. (Original) The chip device of claim 1 wherein the first die is a MOSFET.
 - 1 5. (Original) The chip device of claim 4 wherein the second die is a controller IC.
 - 2 6. (Original) The chip device of claim 1 wherein a drain region of the first die is exposed
 - 3 through the molded body.
 - 1 Claims 7-8 canceled.
-